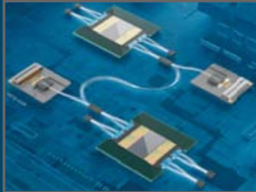
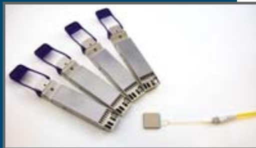
Advanced Packaging Update:

Market and Technology Trends

Vol. 3-1023





This third volume of the Advanced Packaging Update includes an economic analysis and OSAT financials. Developments in co-packaged optics are discussed. An updated analysis of panel fan-out is presented, including new players. A special section examines MicroLEDs, discussing applications and players. A status report on PFAS elimination is provided.

Table of Contents

1 Industry and Economic Trends
- 1.1 Economic Growth Slows
  - 1.1.1 China's Economy
  - 1.1.2 U.S. Macroeconomic Trends
- 1.2 Smartphone and PC Growth
  - 1.2.1 PC Shipments Decline
  - 1.2.2 Smartphone Shipments Decline
    - 1.2.2.1 Apple's Smartphone Growth
    - 1.2.2.2 Huawei's Mate 60 Pro

2 OSAT Financial Analysis
- 2.1 Market Overview
- 2.2 OSAT Market Performance
- 2.3 Company Highlights
  - ASE, Amkor, JCET, TFME, PTI, Huatian, UTAC, KYEC, Chipbond, ChipMOS
- 2.4 Financial Metrics
  - 2.4.1 Gross Margin
  - 2.4.2 R&D
  - 2.4.3 CAPEX
- 2.5 Outlook

3 CPO Developments
- 3.1 Ayar Labs
- 3.2 Broadcom
- 3.3 Cisco
- 3.4 Infinera
- 3.5 Intel
- 3.6 Marvell
- 3.7 OpenLight Photonics
- 3.8 SCINTIL Photonics
- 3.9 TSMC
- 3.10 OSATs
  - Amkor Technology, ASE, IBM Bromont, SPIL
- 3.11 Research Organizations
  - AIM Photonics, CEA-Leti, Fraunhofer IZM, IME, NTT, Tyndall National Institute

4 MicroLEDs
- 4.1 MicroLED Developments
  - Applied Materials, Avicena, Infineon and Nichia, Innovation Semiconductor, Jade Bird Display, Micledi, Mojo Vision, PlayNitride, Porotech, Scrona, Terecircuits, Uniqarta

5 Panel Fan-Out
- 5.1 Advantages for Panel FO
- 5.2 Challenges for Panel FO
- 5.3 Overcoming Challenges for Panel FO
- 5.4 Panel Production Lines
  - Amkor, AOI, ASE, China Wafer Level CSP, ECHINT, Innolux, nepes, PEP Innovation, PTI, Samsung, Unimicron
- 5.5 FO Panel Demand and Capacity

6 PFAS Elimination

References

List of Figures

1.1. Monthly U.S. housing starts.
3.1. ASIC and SCIP CoW assembly.
3.2. Broadcom's detachable optical connector.
3.3. Silicon photonics optical interposer.
3.4. Edge laser vs. embedded laser structure.
3.5. CEA-Leti's Optical Network on Chip system.
3.6. FOWLP for EIC and PIC packaging.
4.1. microLED application spaces and technologies.
4.2. Co-packaged optics with microLEDs.
4.3. Nichia's μPLS integrated microLED light engine.
4.4. Monolithic vertical architecture.
5.1. Amkor panel process.

List of Tables

1.1. Huawei's Packages by Supplier Location
2.1. Top 20 OSATs Quarterly Revenue
2.2. 1H 2022 v. 1H 2023 Top 20 OSAT Revenue
2.3. Historical Gross Margins for Top 10 OSATs
2.4. R&D Spending for Top 10 OSATs
2.5. CAPEX Spending for Top 10 OSATs
4.1. Comparison of Different Display Technologies
4.2. MicroLED Association Members
5.1. FO-WLP Panel Activities
5.2. Annual Panel Demand Forecast
5.3. Annual Panel Capacity
6.1. SIA White Papers on PFAS
6.2. Government Organizations Working on PFAS

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